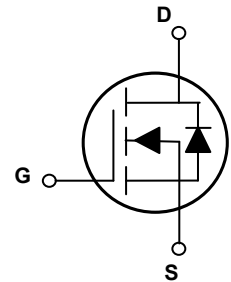
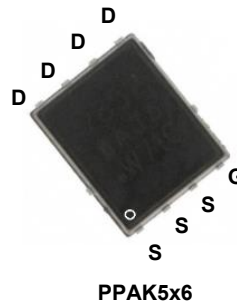


### Main Product Characteristics

$BV_{DSS}$	80V
$R_{DS(ON)}$	2.2m $\Omega$ (Typ.)
$I_D$	170A



Schematic Diagram

### Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



### Description

The GSGP2R608 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

### Absolute Maximum Ratings (T<sub>A</sub>=25°C unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	V <sub>DS</sub>	80	V
Gate-Source Voltage	V <sub>GS</sub>	±20	V
Drain Current-Continuous, @Steady-State (T <sub>C</sub> =25°C)	I <sub>D</sub>	170	A
Drain Current-Continuous, @Steady-State (T <sub>C</sub> =100°C)		110	
Drain Current-Pulsed (T <sub>C</sub> =25°C) <sup>1</sup>	I <sub>DM</sub>	680	A
Single Pulse Avalanche Energy	E <sub>AS</sub>	380	mJ
Single Pulse Avalanche Current	I <sub>AS</sub>	39	A
Power Dissipation (T <sub>C</sub> =25°C) <sup>2</sup>	P <sub>D</sub>	150	W
Thermal Resistance, Junction-to-Ambient (PCB Mounted, Steady-State)	R <sub>θJA</sub>	50	°C/W
Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	0.84	°C/W
Operating Junction Temperature Range	T <sub>J</sub>	-55 To +150	°C
Storage Temperature Range	T <sub>STG</sub>	-55 To +150	°C

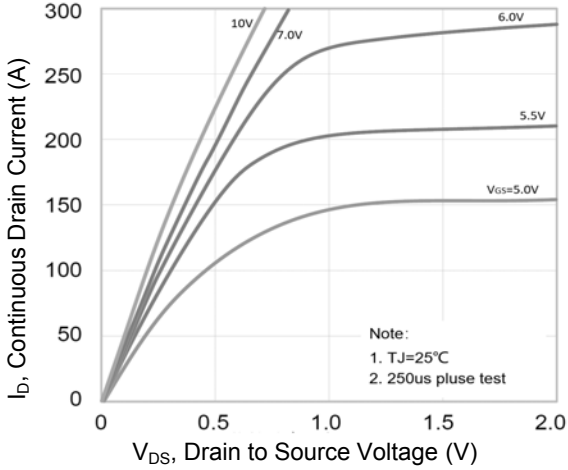
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=250\mu A$	80	-	-	V
Drain-Source Leakage Current	$I_{DSS}$	$V_{DS}=80V, V_{GS}=0V, T_J=25^\circ\text{C}$	-	-	1	$\mu A$
		$V_{DS}=80V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	5.0	-	$\mu A$
Gate-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Static Drain-Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=50A$	-	2.2	2.6	m $\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.1	-	3.9	V
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge <sup>3,4</sup>	$Q_g$	$V_{DD}=40V, I_D=50A, V_{GS}=10V$	-	95	-	nC
Gate-Source Charge <sup>3,4</sup>	$Q_{gs}$		-	37	-	
Gate-Drain ("Miller") Charge <sup>3,4</sup>	$Q_{gd}$		-	17	-	
Gate to Plateau <sup>3,4</sup>	$V_{plateau}$		-	5.5	-	V
Turn-On Delay Time <sup>3,4</sup>	$t_{d(on)}$	$V_{DD}=40V, R_G=3\Omega, V_{GS}=10V, I_D=50A$	-	32	-	nS
Rise Time <sup>3,4</sup>	$t_r$		-	82	-	
Turn-Off Delay Time <sup>3,4</sup>	$t_{d(off)}$		-	80	-	
Fall Time <sup>3,4</sup>	$t_f$		-	34	-	
Input Capacitance	$C_{iss}$	$V_{DS}=40V, V_{GS}=0V, F=1\text{MHz}$	-	6022	-	pF
Output Capacitance	$C_{oss}$		-	846	-	
Reverse Transfer Capacitance	$C_{rss}$		-	37	-	
Gate Resistance	$R_g$	$F=1\text{MHz}$	-	3.4	-	$\Omega$
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>						
Continuous Source Current (Body Diode)	$I_s$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-	170	A
Pulsed Source Current	$I_{s,pulse}$		-	-	680	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_s=50A$	-	-	1.4	V
Reverse Recovery Time <sup>3</sup>	$t_{rr}$	$V_{GS}=0V, I_s=50A, di_f/dt=100A/\mu s$	-	39	-	nS
Reverse Recovery Charge <sup>3</sup>	$Q_{rr}$		-	80	-	nC

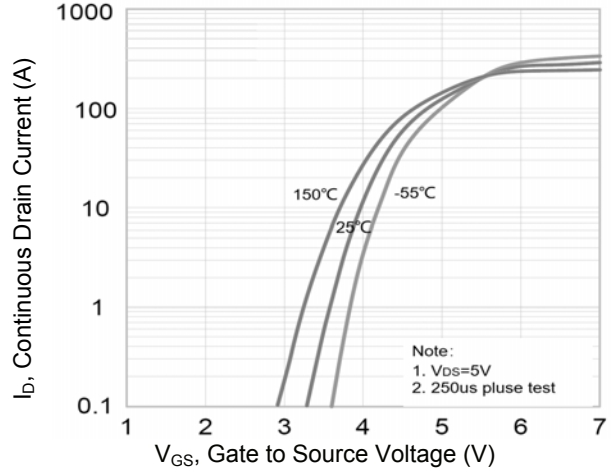
Note:

1. Pulse time of 5us, pulse width limited by maximum junction temperature.
2. The dissipated power value will change with the temperature. When it is greater than 25°C, the dissipated power value will decrease by 1.0°C/W for every 1 degree of temperature increase.
3. Pulse test: Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
4. Essentially independent of operating temperature.

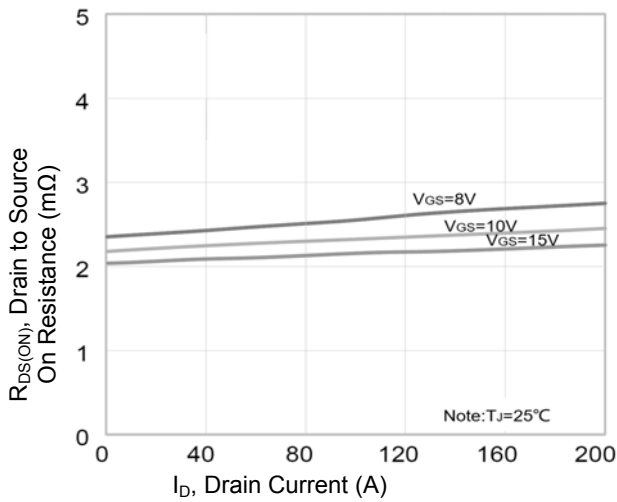
**Typical Electrical and Thermal Characteristic Curves**



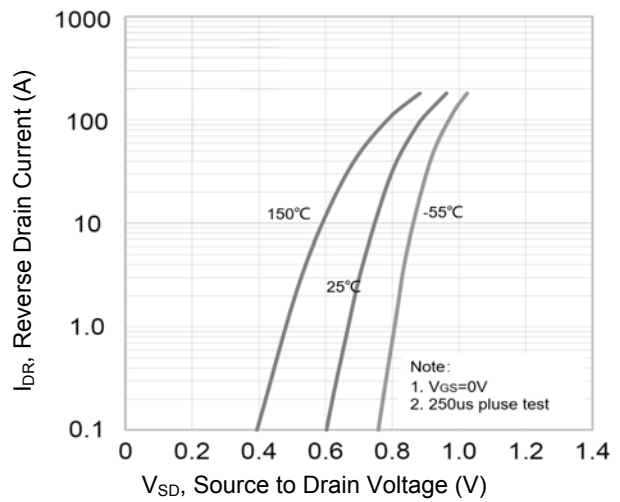
**Figure 1. Typical Output Characteristics**



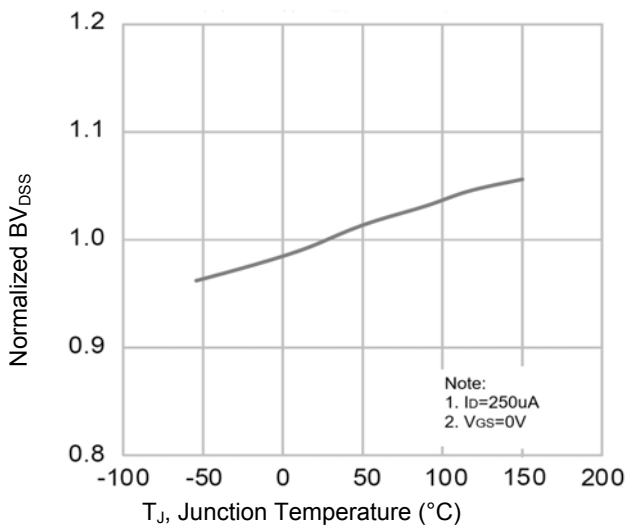
**Figure 2. Transfer Characteristics**



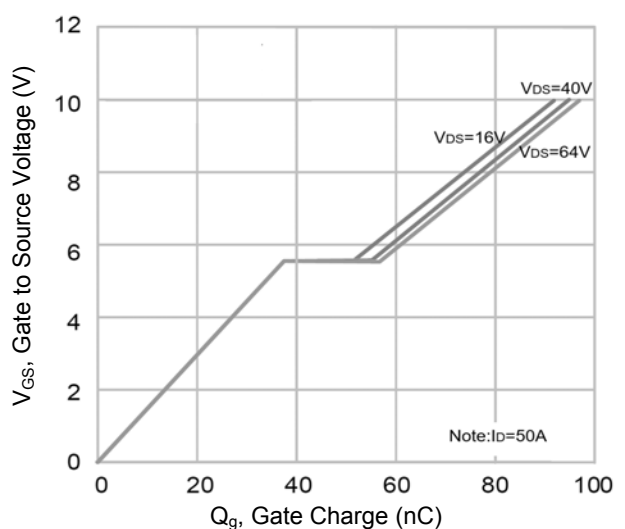
**Figure 3.  $R_{DS(ON)}$  vs. Drain Current**



**Figure 4. Body Diode Characteristics**

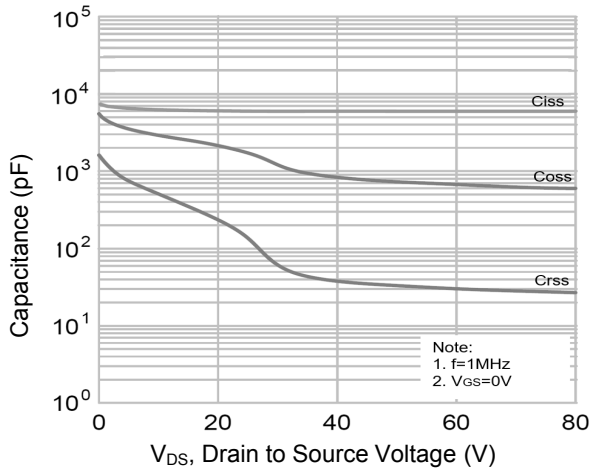


**Figure 5. Normalized  $BV_{DSS}$  vs.  $T_J$**

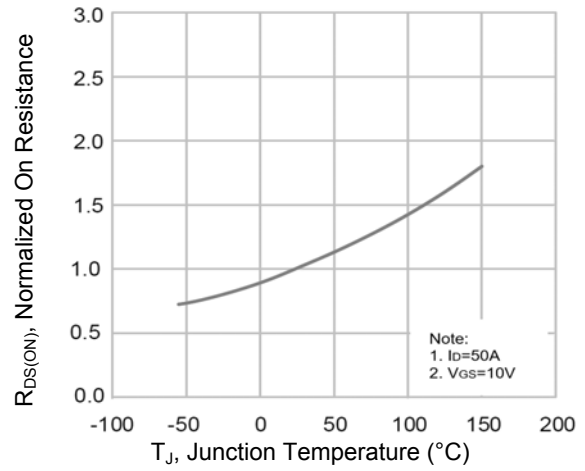


**Figure 6. Gate Charge Characteristics**

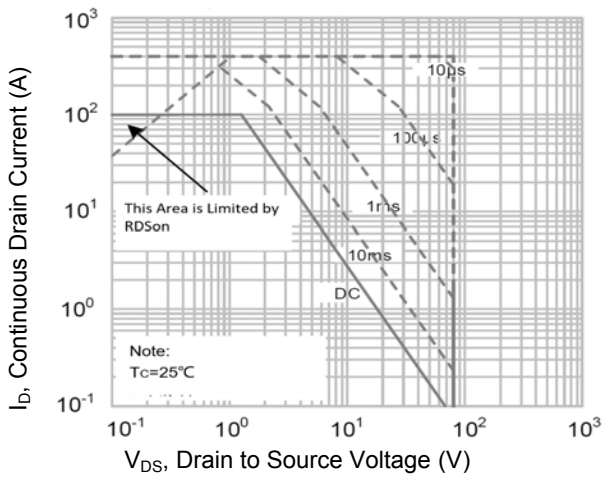
**Typical Electrical and Thermal Characteristic Curves**



**Figure 7. Capacitance Characteristics**

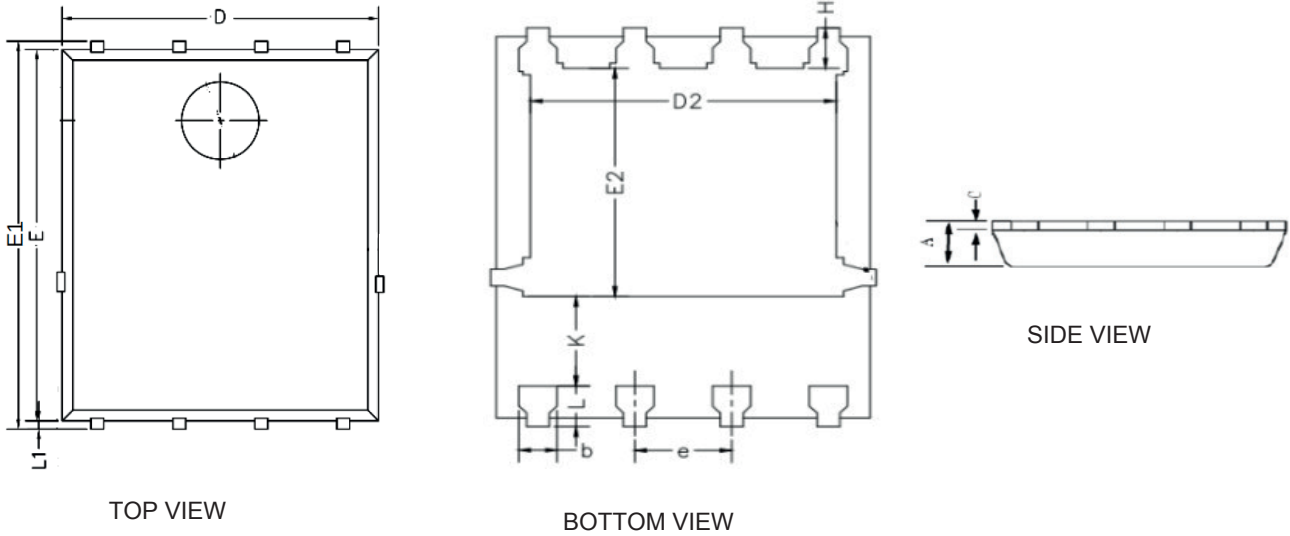


**Figure 8. Normalized R<sub>DS(ON)</sub> vs. T<sub>J</sub>**



**Figure 9. Maximum Safe Operation Area**

**Package Outline Dimensions (PPAK5x6)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.90	1.20	0.035	0.047
b	0.30	0.55	0.012	0.022
C	0.15	0.35	0.006	0.014
D	4.70	5.20	0.185	0.205
D2	3.76	4.20	0.148	0.165
E2	3.30	3.85	0.130	0.152
E	5.60	5.90	0.220	0.232
E1	5.80	6.20	0.228	0.244
K	1.10	-	0.043	-
H	0.45	0.75	0.018	0.030
L	0.45	0.75	0.018	0.030
L1	0.25	0.45	0.010	0.018
e	1.27 BSC		0.050 BSC	

**Order Information**

Device	Package	Marking	Carrier	Quantity
GSGP2R608	PPAK5x6	P2R608	Tape & Reel	5,000 Pcs / Reel

For more information, please contact us at: [inquiry@goodarksemi.com](mailto:inquiry@goodarksemi.com)